



# SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

- Samsung P/N : **CL31B225KBHNFNE**
- Description : **CAP, 2.2 $\mu$ F, 50V,  $\pm$ 10%, X7R, 1206**

## A. Samsung Part Number

**CL 31 B 225 K B H N F N E**  
 ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

|                                |                                       |                                      |                               |
|--------------------------------|---------------------------------------|--------------------------------------|-------------------------------|
| ① <b>Series</b>                | Samsung Multi-layer Ceramic Capacitor |                                      |                               |
| ② <b>Size</b>                  | 1206 (inch code)                      | L: 3.2 $\pm$ 0.2 mm                  | W: 1.6 $\pm$ 0.2 mm           |
| ③ <b>Dielectric</b>            | X7R                                   | ⑧ <b>Inner electrode Termination</b> | Ni                            |
| ④ <b>Capacitance</b>           | 2.2 $\mu$ F                           | ⑨ <b>Plating</b>                     | Cu                            |
| ⑤ <b>Capacitance tolerance</b> | $\pm$ 10 %                            | ⑩ <b>Product</b>                     | Sn 100% (Pb Free)             |
| ⑥ <b>Rated Voltage</b>         | 50 V                                  | ⑪ <b>Special</b>                     | Product for POWER application |
| ⑦ <b>Thickness</b>             | 1.6 $\pm$ 0.2 mm                      |                                      | Reserved for future use       |
|                                |                                       |                                      | Embossed Type, 7" reel        |

## B. Samsung Reliability Test and Judgement condition

|   | Performance   | Test condition   |
|---|---|--|
| <b>Capacitance</b>                      | Within specified tolerance  | 1kHz $\pm$ 10%<br>1.0 $\pm$ 0.2Vrms  |
| <b>Tan <math>\delta</math> (DF)</b>     | 0.1 max.  |  |
| <b>Insulation Resistance</b>            | 10,000Mohm or 100Mohm $\cdot\mu$ F<br>Whichever is Smaller  | Rated Voltage 60~120 sec.  |
| <b>Appearance</b>                       | No abnormal exterior appearance   | Microscope ( $\times$ 10)  |
| <b>Withstanding Voltage</b>             | No dielectric breakdown or mechanical breakdown   | 250% of the rated voltage  |
| <b>Temperature Characterisitcs</b>      | X7R<br>(From -55 $^{\circ}$ C to 125 $^{\circ}$ C, Capacitance change should be within $\pm$ 15%) |  |
| <b>Adhesive Strength of Termination</b> | No peeling shall be occur on the terminal electrode   | 500g $\cdot$ F, for 10 $\pm$ 1 sec.  |
| <b>Bending Strength</b>                 | Capacitance change : within $\pm$ 12.5%   | Bending to the limit (1mm) with 1.0mm/sec.   |
| <b>Solderability</b>                    | More than 75% of terminal surface is to be soldered newly   | SnAg3.0Cu0.5 solder<br>245 $\pm$ 5 $^{\circ}$ C, 3 $\pm$ 0.3sec.<br>(preheating : 80~120 $^{\circ}$ C for 10~30sec.) |
| <b>Resistance to Soldering heat</b>     | Capacitance change : within $\pm$ 7.5%<br>Tan $\delta$ , IR : initial spec.                       | Solder pot : 270 $\pm$ 5 $^{\circ}$ C, 10 $\pm$ 1sec.  |

|                                    | <b>Performance</b>  | <b>Test condition</b>   |
|------------------------------------|---|---|
| <b>Vibration Test</b>              | Capacitance change : within $\pm 5\%$<br>Tan $\delta$ , IR : initial spec.                                      | Amplitude : 1.5mm<br>From 10Hz to 55Hz (return : 1min.)<br>2hours $\times$ 3 direction (x, y, z)  |
| <b>Moisture Resistance</b>         | Capacitance change : within $\pm 12.5\%$<br>Tan $\delta$ : 0.125 max<br>IR : 12.5M $\Omega \cdot \mu F$ or Over | With rated voltage<br>40 $\pm 2$ °C, 90~95%RH, 500+12/-0hrs   |
| <b>High Temperature Resistance</b> | Capacitance change : within $\pm 12.5\%$<br>Tan $\delta$ : 0.125 max<br>IR : 25M $\Omega \cdot \mu F$ or Over   | With 150% of the rated voltage<br>Max. operating temperature<br><br>1000+48/-0hrs   |
| <b>Temperature Cycling</b>         | Capacitance change : within $\pm 7.5\%$<br>Tan $\delta$ , IR : initial spec.                                    | 1 cycle condition<br>Min. operating temperature $\rightarrow$ 25°C<br>$\rightarrow$ Max. operating temperature $\rightarrow$ 25°C<br><br>5 cycle test |

**C. Recommended Soldering method :**

Reflow ( Reflow Peak Temperature : 260+0/-5°C, 10sec. Max )

\* For the more detail Specification, Please refer to the Samsung MLCC catalogue.